



40V N-Channel Enhancement Mode MOSFET

Voltage

40 V

Current

192 A

Features

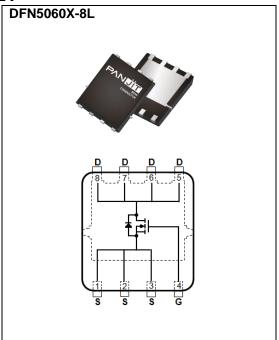
- R_{DS(ON)}, V_{GS}@10V, I_D@20A<1.88mΩ
- RDS(ON), VGS@4.5V, ID@20A<2.5m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060X-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.087 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	40	- V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C	l _D	192		
	T _C =100°C		136	Α	
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	672		
Power Dissipation	T _C =25°C	Do	125	W	
	T _C =100°C	Po	63		
Continuous Drain Current(Note 4)	T _A =25°C	l _D	31		
	T _A =70°C		26	Α	
Power Dissipation	T _A =25°C	₽o	3.3	W	
	T _A =70°C	PD	2.3		
Single Pulse Avalanche Energy ^(Note 5)		Eas	462	mJ	
Operating Junction and Storage Temperature Range		T_{J} , T_{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{0JC}	1.2	°C/W	
	Junction to Ambient	$R_{\theta JA}$	45		





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	40	-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =50uA	1.1	1.4	2.3		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	1.5	1.88	mΩ	
		V _{GS} =4.5V, I _D =20A	-	1.9	2.5		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)	•		1				
Total Gate Charge	Q_g	V _{DS} =32V, I _D =20A,	-	75	-	nC	
Gate-Source Charge	Qgs		-	15	-		
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	10	-		
Input Capacitance	Ciss		-	4950	-	pF	
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V,	-	1250	-		
Reverse Transfer Capacitance	Crss	f=1MHz	-	170	-		
Gate resistance	Rg	f=1MHz	-	1	-	Ω	
Turn-On Delay Time	td _(on)		-	20	-	ns	
Turn-On Rise Time	tr	V _{DS} =32V, I _D =20A,	-	32	-		
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$	-	68	-		
Turn-Off Fall Time	tf	(Note 2)	-	17	-		
Drain-Source Diode	•		1		•	•	
Diode Forward Current	Is	T 05°0	-	-	192		
Pulsed Diode Forward Current	I _{SM}	T _C =25°C	-	-	672	Α	
Diode Forward Voltage	V _{SD}	Is=20A, Vgs=0V	-	0.8	1.3	V	
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	-	52	-	ns	
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	50	-	nC	

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an $R_{\theta JC}$ =1.2°C/W, Package limited 100A.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I_{AS}=43A, V_{DD}=30V, V_{GS}=10V, Starting T_J=25°C.
- 6. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

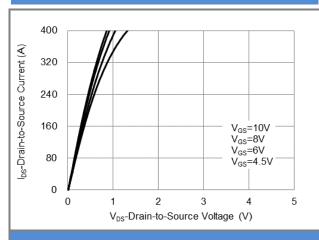


Fig.1 On-Region Characteristics

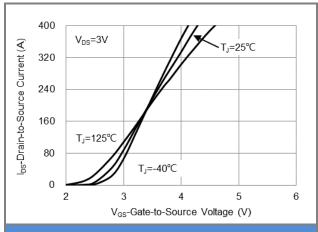


Fig.2 Transfer Characteristics

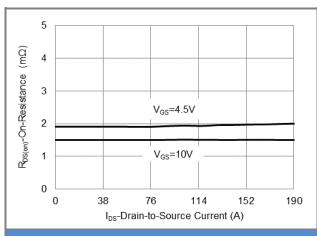


Fig.3 On-Resistance vs. Drain Current

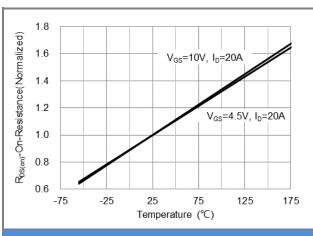
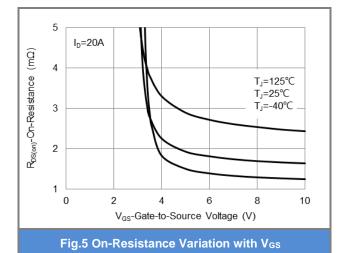
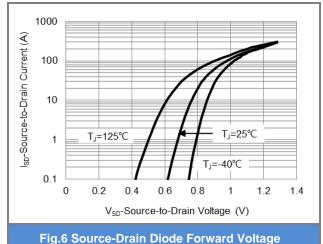


Fig.4 On-Resistance vs. Junction temperature









TYPICAL CHARACTERISTIC CURVES

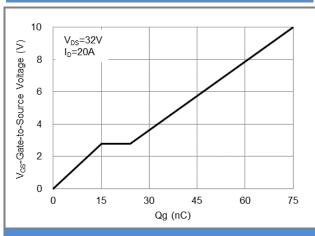


Fig.7 Gate-Charge Characteristics

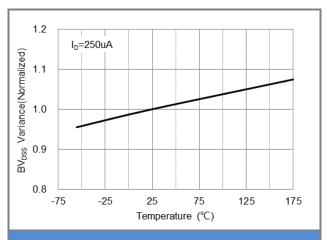


Fig.8 Breakdown Voltage Variation vs. Temperature

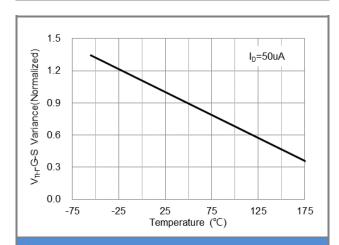


Fig.9 Threshold Voltage Variation with Temperature

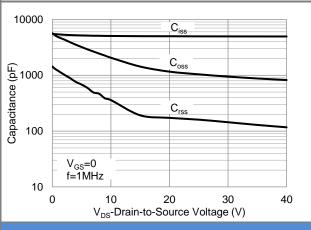
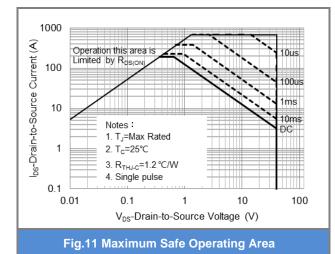


Fig.10 Capacitance vs. Drain-Source Voltage



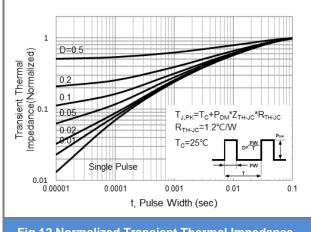


Fig.12 Normalized Transient Thermal Impedance

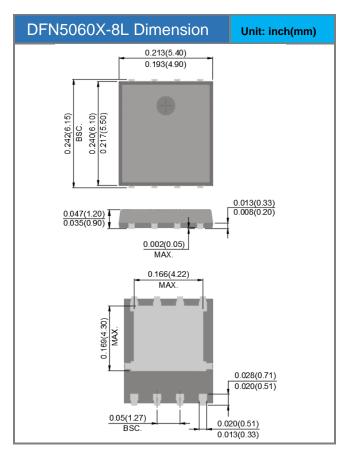


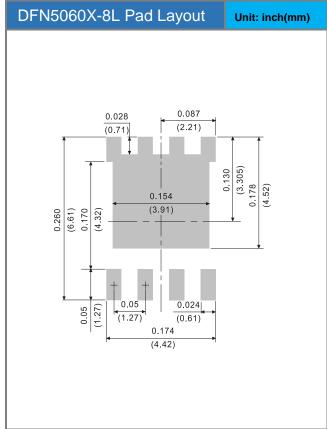


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJQ5540-AU	DFN5060X-8L	3K pcs / 13" reel	Q5540	

Packaging Information & Mounting Pad Layout









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